# 20 V, 4.0 A, Low V<sub>CE(sat)</sub> PNP Transistor

ON Semiconductor's  $e^2$ PowerEdge family of low  $V_{CE(sat)}$  transistors are miniature surface mount devices featuring ultra low saturation voltage ( $V_{CE(sat)}$ ) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

#### **Features**

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



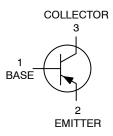
#### ON Semiconductor®

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# $\begin{array}{c} -20 \text{ VOLTS} \\ 4.0 \text{ AMPS} \\ \text{PNP LOW V}_{\text{CE(sat)}} \text{ TRANSISTOR} \\ \text{EQUIVALENT R}_{\text{DS(on)}} \text{ 65 m} \Omega \end{array}$



SOT-23 (TO-236) CASE 318 STYLE 6



#### **MARKING DIAGRAM**



VC = Specific Device Code

M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)
\*Date Code orientation and/or overbar may
vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSS20200LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
NSV20200LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### **MAXIMUM RATINGS** $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit	
Collector-Emitter Voltage	V <sub>CEO</sub>	-20	Vdc	
Collector-Base Voltage	V <sub>CBO</sub>	-20	Vdc	
Emitter-Base Voltage	V <sub>EBO</sub>	-7.0	Vdc	
Collector Current - Continuous	I <sub>C</sub>	-2.0	Α	
Collector Current - Peak	I <sub>CM</sub>	-4.0	А	
Electrostatic Discharge	ESD	HBM Class 3B MM Class C		

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 1)	460 3.7	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 1)	270	°C/W
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 2)	540 4.3	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 2)	230	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P <sub>Dsingle</sub> (Note 3)	710	mW
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-4 @ 100 mm², 1 oz. copper traces.

2. FR-4 @ 500 mm², 1 oz. copper traces.

3. Thermal response.

#### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•		•
Collector – Emitter Breakdown Voltage ( $I_C = -10$ mAdc, $I_B = 0$ )	V <sub>(BR)</sub> CEO	-20	-	_	Vdc
Collector – Base Breakdown Voltage $(I_C = -0.1 \text{ mAdc}, I_E = 0)$	V <sub>(BR)</sub> CBO	-20	-	-	Vdc
Emitter – Base Breakdown Voltage $(I_E = -0.1 \text{ mAdc}, I_C = 0)$	V <sub>(BR)EBO</sub>	-7.0	-	-	Vdc
Collector Cutoff Current (V <sub>CB</sub> = -20 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	_	-	-0.1	μAdc
Emitter Cutoff Current (V <sub>EB</sub> = -7.0 Vdc)	I <sub>EBO</sub>	_	-	-0.1	μAdc
ON CHARACTERISTICS	<u>.</u>				
DC Current Gain (Note 4) $ \begin{array}{l} (I_C = -10 \text{ mA, } V_{CE} = -2.0 \text{ V}) \\ (I_C = -500 \text{ mA, } V_{CE} = -2.0 \text{ V}) \\ (I_C = -500 \text{ mA, } V_{CE} = -2.0 \text{ V}) \\ (I_C = -1.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \\ (I_C = -2.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \end{array} $	h <sub>FE</sub>	250 250 180 150	- 300 - -	- - - -	
Collector – Emitter Saturation Voltage (Note 4) $ \begin{pmatrix} I_C = -0.1 \text{ A, } I_B = -0.010 \text{ A} \end{pmatrix} \text{ (Note 5)} \\ \begin{pmatrix} I_C = -1.0 \text{ A, } I_B = -0.100 \text{ A} \end{pmatrix} \\ \begin{pmatrix} I_C = -1.0 \text{ A, } I_B = -0.010 \text{ A} \end{pmatrix} \\ \begin{pmatrix} I_C = -2.0 \text{ A, } I_B = -0.200 \text{ A} \end{pmatrix} $	V <sub>CE(sat)</sub>	- - - -	-0.008 -0.065 -0.100 -0.130	-0.013 -0.090 -0.120 -0.180	V
Base – Emitter Saturation Voltage (Note 4) $(I_C = -1.0 \text{ A}, I_B = -0.01 \text{ A})$	V <sub>BE(sat)</sub>	-	-	-0.900	V
Base – Emitter Turn–on Voltage (Note 4) (I <sub>C</sub> = -1.0 A, V <sub>CE</sub> = -2.0 V)	V <sub>BE(on)</sub>	-	-	-0.900	V
Cutoff Frequency ( $I_C = -100 \text{ mA}$ , $V_{CE} = -5.0 \text{ V}$ , $f = 100 \text{ MHz}$ )	f <sub>T</sub>	100	-	_	MHz
Input Capacitance (V <sub>EB</sub> = 0.5 V, f = 1.0 MHz)	Cibo	-	-	330	pF
Output Capacitance (V <sub>CB</sub> = 3.0 V, f = 1.0 MHz)	Cobo	-	-	100	pF
SWITCHING CHARACTERISTICS					
Delay (V <sub>CC</sub> = -15 V, I <sub>C</sub> = 750 mA, I <sub>B1</sub> = 15 mA)	t <sub>d</sub>	-	_	60	ns
Rise (V <sub>CC</sub> = -15 V, I <sub>C</sub> = 750 mA, I <sub>B1</sub> = 15 mA)	t <sub>r</sub>	-	-	120	ns
Storage ( $V_{CC} = -15 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$ )	t <sub>s</sub>	-	_	300	ns
Fall ( $V_{CC} = -15 \text{ V}, I_{C} = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$ )	t <sub>f</sub>	=	-	130	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

5. Guaranteed by design but not tested.

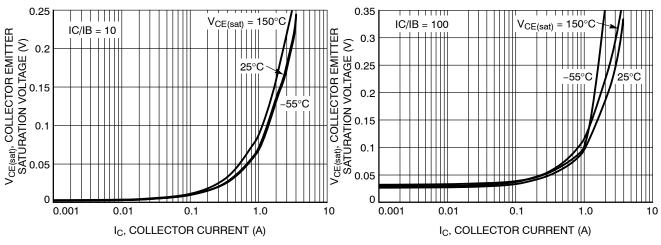


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

Figure 2. Collector Emitter Saturation Voltage vs. Collector Current

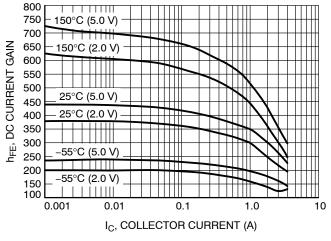


Figure 3. DC Current Gain vs. Collector Current

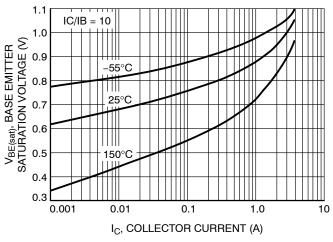


Figure 4. Base Emitter Saturation Voltage vs. Collector Current

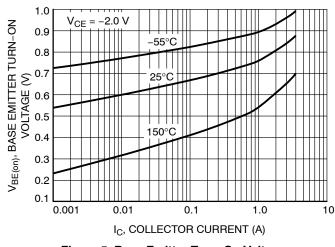


Figure 5. Base Emitter Turn-On Voltage vs. Collector Current

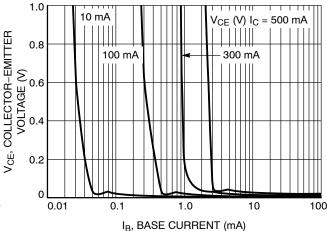
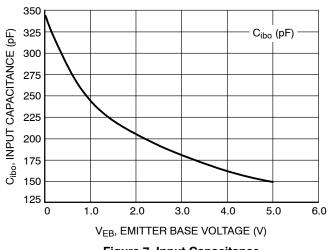


Figure 6. Saturation Region



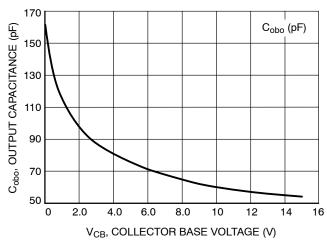


Figure 7. Input Capacitance

Figure 8. Output Capacitance

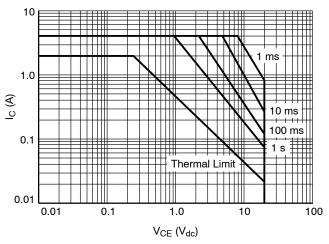
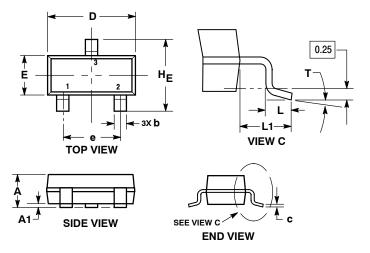


Figure 9. Safe Operating Area

#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR** 



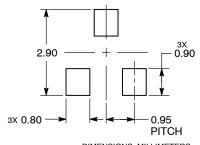
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETERS.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
  MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
- PROTRUSIONS, OR GATE BURRS.

		M	ILLIMETE	RS		;	
DI	М	MIN	NOM	MAX	MIN	NOM	MAX
- 4	١.	0.89	1.00	1.11	0.035	0.039	0.044
Α	1	0.01	0.06	0.10	0.000	0.002	0.004
b	•	0.37	0.44	0.50	0.015	0.017	0.020
	``	0.08	0.14	0.20	0.003	0.006	0.008
		2.80	2.90	3.04	0.110	0.114	0.120
E	Ξ.	1.20	1.30	1.40	0.047	0.051	0.055
e	•	1.78	1.90	2.04	0.070	0.075	0.080
L	_	0.30	0.43	0.55	0.012	0.017	0.022
L	1	0.35	0.54	0.69	0.014	0.021	0.027
Н	Е	2.10	2.40	2.64	0.083	0.094	0.104
T		0°		10 °	0 °		10 °

#### STYLE 6

- PIN 1. BASE
  - **EMITTER** 2
  - COLLECTOR

#### RECOMMENDED **SOLDERING FOOTPRINT\***



**DIMENSIONS: MILLIMETERS** 

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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